

# TISP4SxxxBJ Overvoltage Protector Series

**BOURNS®**

## How to Order

Device	Package	Carrier	Order As
TISP4SxxxzBJ	BJ (J-Bend DO-214AA/SMB)	Embossed Tape Reeled	TISP4SxxxzBJR-S

Insert xxx value corresponding to protection voltages.

## Absolute Maximum Ratings, $T_A = 25^\circ\text{C}$ (Unless Otherwise Noted)

Parameter	Symbol	Value	Unit
Repetitive peak off-state voltage	$V_{\text{DRM}}$	TISP4S040L1BJR-S $\pm 25$	V
		TISP4S040M1BJR-S $\pm 25$	
		TISP4S077M3BJR-S $\pm 58$	
		TISP4S088M3BJR-S $\pm 65$	
		TISP4S098M3BJR-S $\pm 75$	
		TISP4S160M3BJR-S $\pm 120$	
		TISP4S180M3BJR-S $\pm 140$	
		TISP4S240M3BJR-S $\pm 180$	
		TISP4S260M3BJR-S $\pm 190$	
		TISP4S300M3BJR-S $\pm 220$	
		TISP4S350M3BJR-S $\pm 275$	
		TISP4S350T3BJR-S $\pm 275$	
		TISP4S400M3BJR-S $\pm 300$	
Non-repetitive peak on-state pulse current 10/1000 $\mu\text{s}$ (GR-1089-CORE, 10/1000 $\mu\text{s}$ voltage wave shape)	$I_{\text{TSP}}$	TISP4SxxxLyBJR-S 30	A
		TISP4SxxxMyBJR-S 50	
		TISP4SxxxT3BJR-S 80	
Operating Temperature	$T_J$	-40 to +150	$^\circ\text{C}$
Storage Temperature	$T_{\text{STG}}$	-55 to +150	$^\circ\text{C}$

## Thermal Characteristics, $T_A = 25^\circ\text{C}$ (Unless Otherwise Noted)

Parameter	Test Conditions	Min.	Nom.	Max.	Unit
$R\theta_{JA}$ Junction to free air thermal resistance	EIA/JESD51-3 PCB, $I_T = I_{\text{TSM}}(1000)$ , $T_A = 25^\circ\text{C}$		115		$^\circ\text{C/W}$

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Specifications are subject to change without notice.

The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

## Parameter Measurement Information

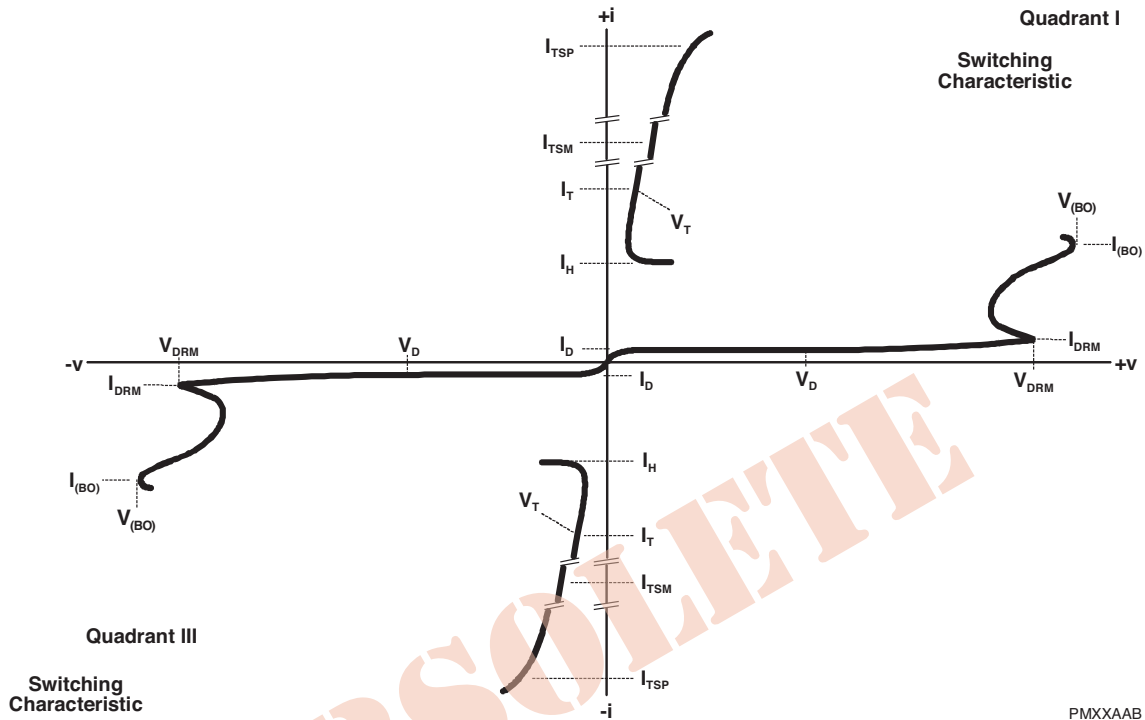
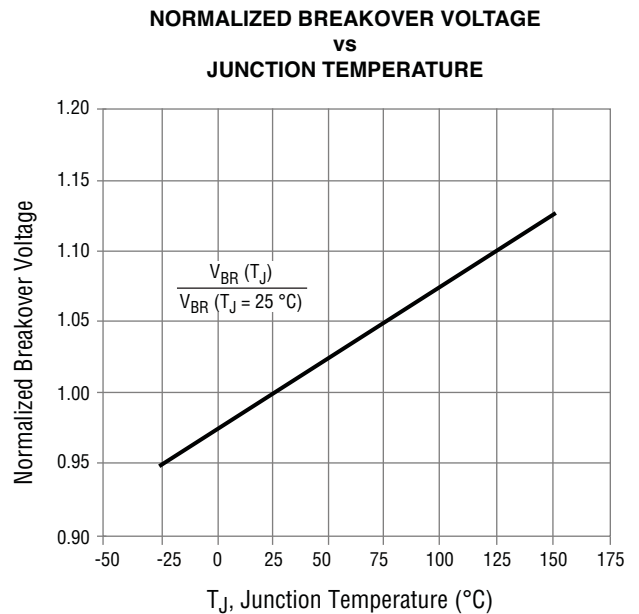
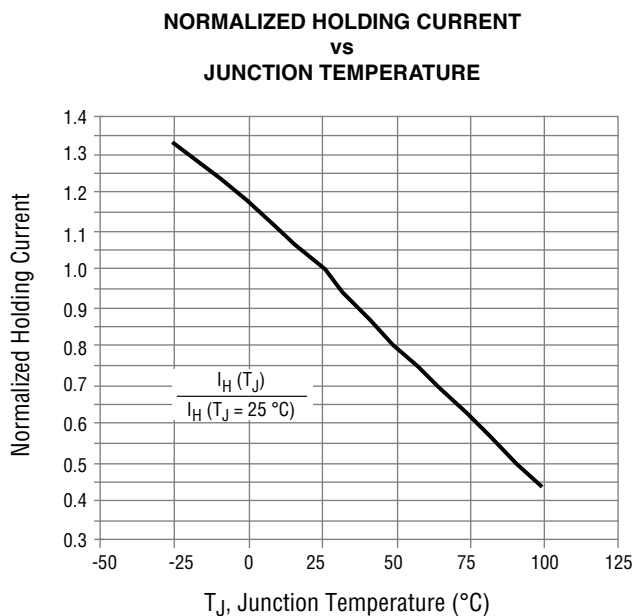


Figure 1. Voltage-current Characteristic for T and R Terminals  
All Measurements are Referenced to the R Terminal

## Typical Characteristics



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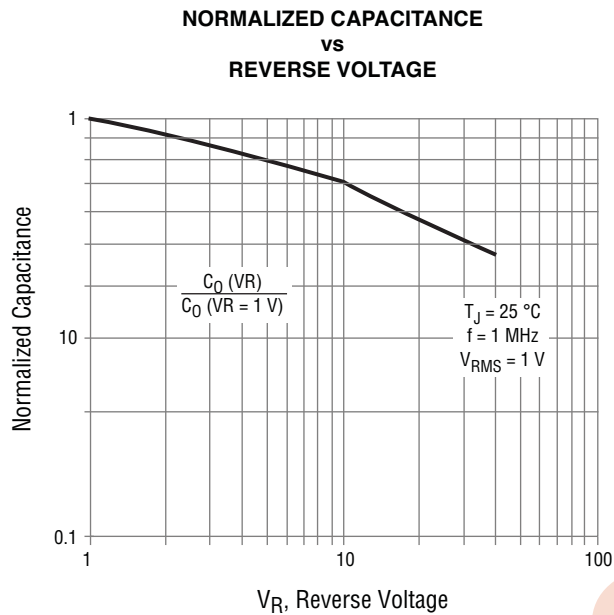
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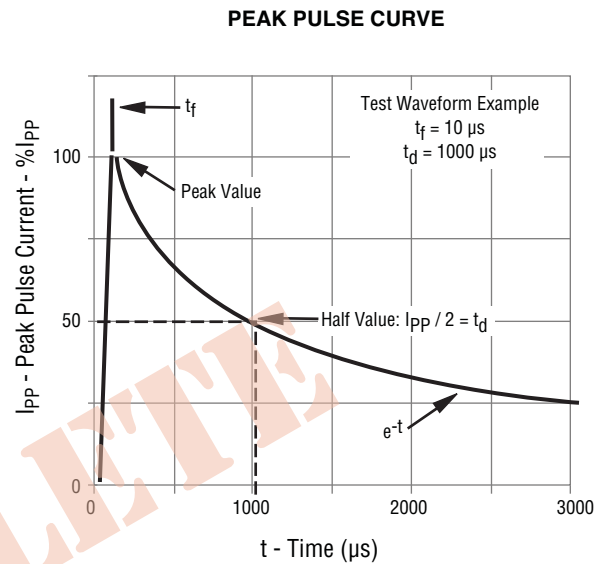
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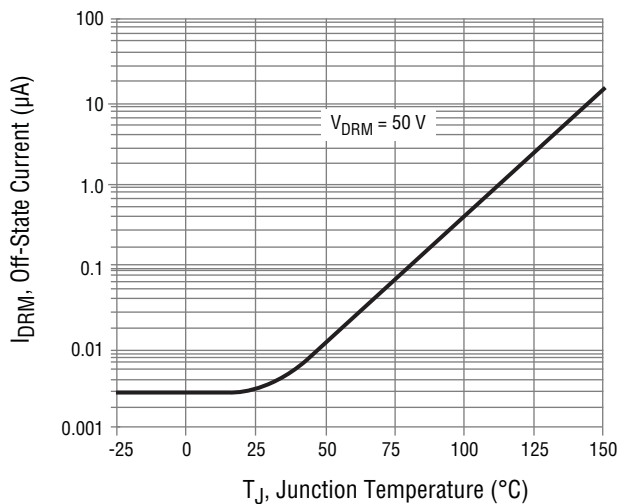
## Typical Characteristics



Excludes TISP4S040x1BJ devices as these are only rated up to 25 V.



## OFF-STATE CURRENT vs JUNCTION TEMPERATURE



Excludes TISP4S040x1BJ devices as these devices cannot be operated at 50 V.

## Device Symbolization Code

Devices will be coded as below. As the device parameters are symmetrical, terminal 1 is not identified.

Device	Symbolization Code
TISP4S040L1BJR-S	KBL
TISP4S040M1BJR-S	GBL
TISP4S077M3BJR-S	GCL
TISP4S088M3BJR-S	GDL
TISP4S098M3BJR-S	GEL
TISP4S160M3BJR-S	GGL
TISP4S180M3BJR-S	GHL
TISP4S240M3BJR-S	GIL
TISP4S260M3BJR-S	GJL
TISP4S300M3BJR-S	GKL
TISP4S350M3BJR-S	GLL
TISP4S350T3BJR-S	GYL
TISP4S400M3BJR-S	GML

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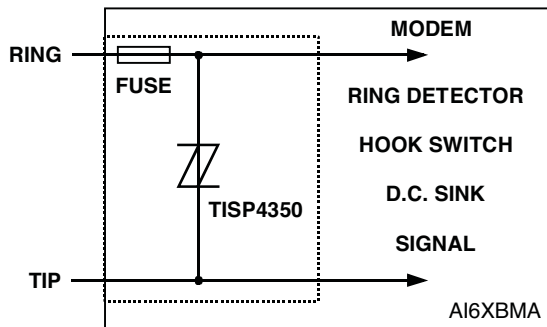
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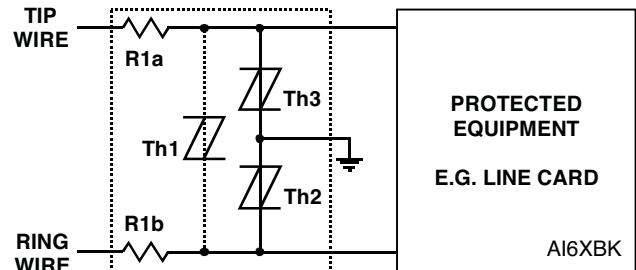
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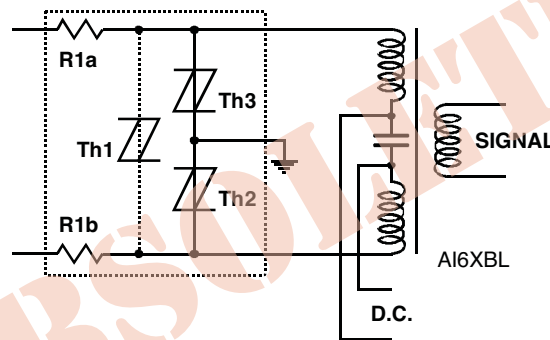
## Typical Applications



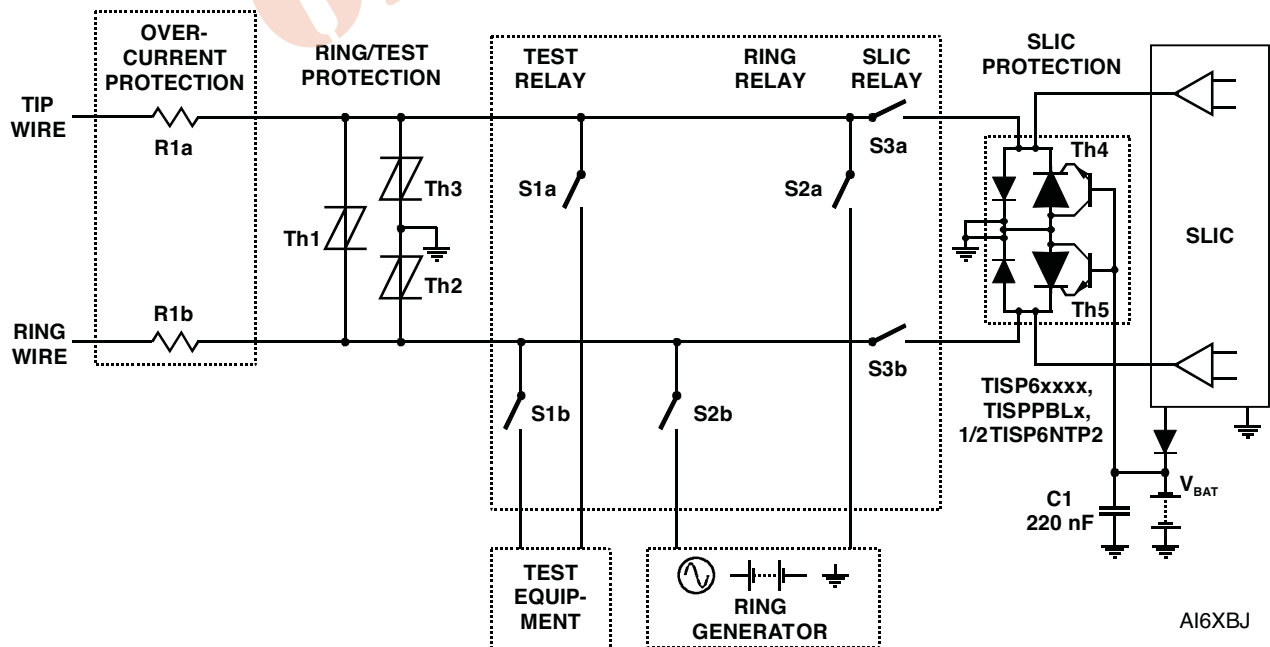
Modem Inter-wire Protection



Protection Module



ISDN Protection



Line Card Ring/Test Protection

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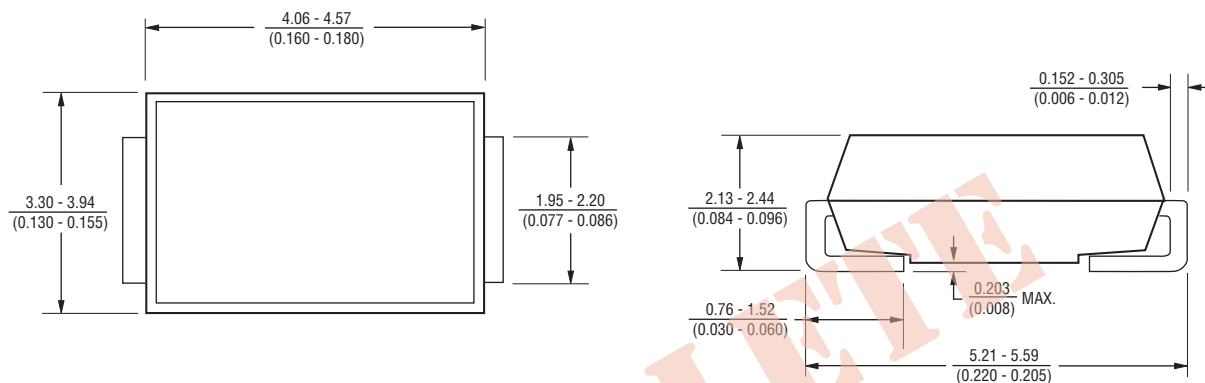
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## Package Outline Dimensions

This surface mount two terminal package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound is designed to withstand normal soldering temperatures with no deformation and circuit performance characteristics will remain stable when operated in most high humidity conditions. Terminals require no additional cleaning or processing when used in soldered assembly.

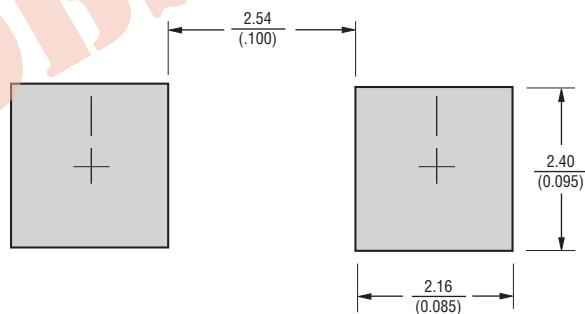
### SMB (DO-214AA) Package



DIMENSIONS ARE : MILLIMETERS  
(INCHES)

## Recommended Printed Wiring Land Pattern Dimensions

### SMB (DO-214AA) Land Pattern



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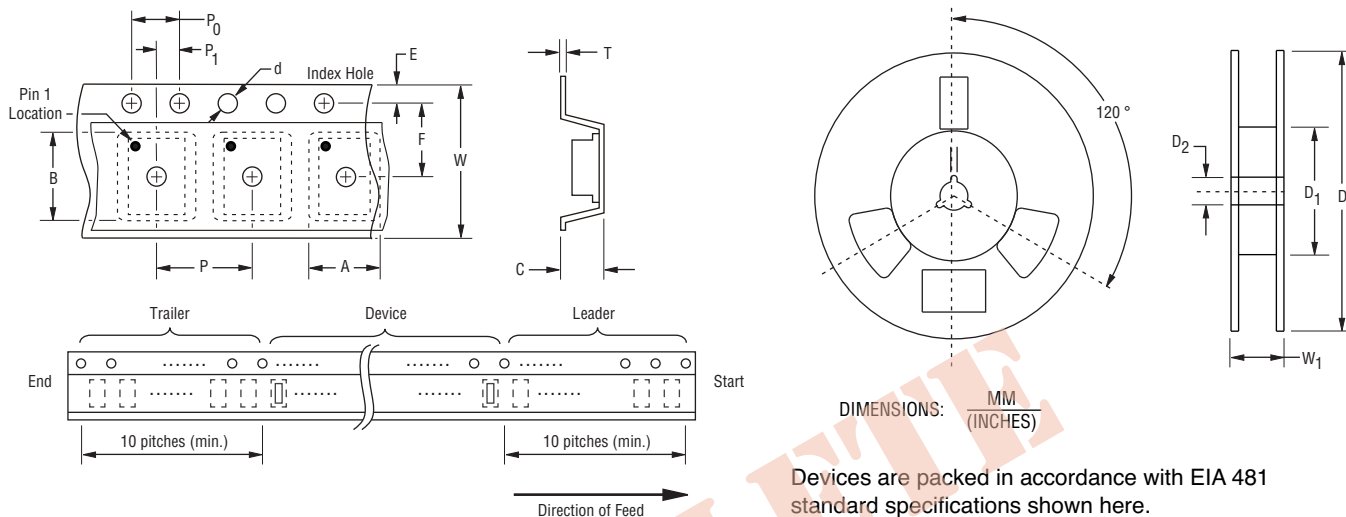
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## Tape & Reel Dimensions

The product will be dispensed in tape and reel format (see diagram below).



Item	Symbol	SMB (DO-214AA)
Carrier Width	A	$4.94 \pm 0.10$ (0.194 - 0.004)
Carrier Length	B	$5.57 \pm 0.10$ (0.210 ± 0.004)
Carrier Depth	C	$2.36 \pm 0.10$ (0.093 ± 0.004)
Sprocket Hole	d	$1.55 \pm 0.05$ (0.061 ± 0.002)
Reel Outside Diameter	D	$330$ (12.992)
Reel Inner Diameter	D <sub>1</sub>	$50.0$ (1.969) MIN.
Feed Hole Diameter	D <sub>2</sub>	$13.0 \pm 0.20$ (0.512 ± 0.008)
Sprocket Hole Position	E	$1.75 \pm 0.10$ (0.069 ± 0.004)
Punch Hole Position	F	$5.50 \pm 0.05$ (0.217 ± 0.002)
Punch Hole Pitch	P	$4.00 \pm 0.10$ (0.157 ± 0.004)
Sprocket Hole Pitch	P <sub>0</sub>	$4.00 \pm 0.10$ (0.157 ± 0.004)
Embossment Center	P <sub>1</sub>	$2.00 \pm 0.05$ (0.079 ± 0.002)
Overall Tape Thickness	T	$0.30 \pm 0.10$ (0.012 ± 0.004)
Tape Width	W	$12.00 \pm 0.20$ (0.472 ± 0.008)
Reel Width	W <sub>1</sub>	$18.4$ (0.724) MAX.
Quantity per Reel	--	3,000

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